Features

- **Fast Read Access Time – 55 ns**
- **Low-power CMOS Operation**
  - **100 µA Max. Standby**
  - **25 mA Max. Active at 5 MHz**
- **JEDEC Standard Packages**
  - **32-lead 600-mil PDIP**
  - **32-lead PLCC**
  - **32-lead TSOP**
- **5V ± 10% Supply**
- **High-reliability CMOS Technology**
  - **2,000V ESD Protection**
  - **200 mA Latch-up Immunity**
- **Rapid™ Programming Algorithm – 100 µs/Byte (Typical)**
- **CMOS- and TTL-compatible Inputs and Outputs**
- **Integrated Product Identification Code**
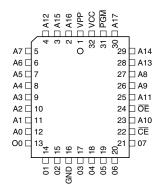- **Commercial, Industrial and Automotive Temperature Ranges**

Description

The AT27C020 is a low-power, high performance, 2,097,152-bit, one-time programmable read-only memory (OTP EPROM) organized as 256K by 8 bits. It requires only one 5V power supply in normal read mode operation. Any byte can be accessed in less than 55 ns, eliminating the need for speed-reducing WAIT states on high-performance microprocessor systems. *(continued)*
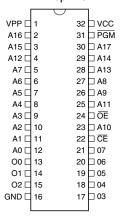
Pin Configurations

Pin Name	Function
A0 - A17	Addresses
O0 - O7	Outputs
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
$\overline{PGM}$	Program Strobe

PLCC Top View

PDIP Top View

TSOP Top View
Type 1

Rev. 0570D–05/00

In read mode, the AT27C020 typically consumes 8 mA. Standby mode supply current is typically less than 10 µA.

The AT27C020 is available in a choice of industry-standard JEDEC-approved one-time programmable (OTP) plastic PDIP, PLCC and TSOP packages. All devices feature two-line control ($\overline{CE}$, $\overline{OE}$) to give designers the flexibility to prevent bus contention.
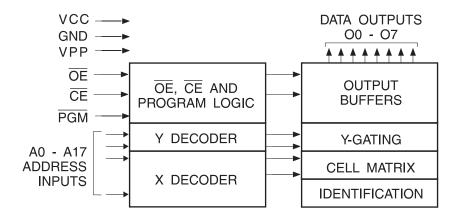
With 256K bytes storage capability, the AT27C020 allows firmware to be stored reliably and to be accessed by the system without the delays of mass storage media.

Atmel's 27C020 have additional features to ensure high quality and efficient production use. The Rapid™ Programming Algorithm reduces the time required to program the part and guarantees reliable programming. Programming time is typically only 100 µs/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry-standard programming equipment to select the proper programming algorithms and voltages.

System Considerations

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed datasheet limits, resulting in device non-conformance. At a minimum, a 0.1 µF high-frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the V_{CC} and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply-voltage level on printed circuit boards with large EPROM arrays, a 4.7 µF bulk electrolytic capacitor should be utilized, again connected between the V_{CC} and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

Block Diagram

Absolute Maximum Ratings*

Temperature under Bias .... -55°C to +125°C
Storage Temperature .... -65°C to +150°C
Voltage on Any Pin with Respect to Ground ....-2.0V to +7.0V[1]
Voltage on A9 with Respect to Ground ....-2.0V to +14.0V[1]
V_{PP} Supply Voltage with Respect to Ground ....-2.0V to +14.0V[1]

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: 1. Minimum voltage is -0.6V DC, which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is V_{CC} + 0.75V DC, which may overshoot to +7.0V for pulses of less than 20 ns.

Operating Modes

Mode/Pin	$\overline{CE}$	$\overline{OE}$	$\overline{PGM}$	Ai	V_{PP}	Outputs
Read	V_{IL}	V_{IL}	X[1]	Ai	X	D_{OUT}
Output Disable	X	V_{IH}	X	X	X	High-Z
Standby	V_{IH}	X	X	X	X	High-Z
Rapid Program[2]	V_{IL}	V_{IH}	V_{IL}	Ai	V_{PP}	D_{IN}
PGM Verify	V_{IL}	V_{IL}	V_{IH}	Ai	V_{PP}	D_{OUT}
PGM Inhibit	V_{IH}	X	X	X	V_{PP}	High-Z
Product Identification[4]	V_{IL}	V_{IL}	X	A9 = V_H[3] A0 = V_{IH} or V_{IL} A1 - A17 = V_{IL}	X	Identification Code

Notes: 1. X can be V_{IL} or V_{IH}.

2. Refer to Programming Characteristics.

3. V_H = 12.0 ± 0.5V.

4. Two identifier bytes may be selected. All Ai inputs are held low (V_{IL}) except A9, which is set to V_H and A0, which is toggled low (V_{IL}) to select the Manufacturer's Identification byte and high (V_{IH}) to select the Device Code byte.

DC and AC Operating Conditions for Read Operation

		AT27C020				
		-55	**-70**	**-90**	**-12**	**-15**
Operating Temperature (Case)	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C	0°C - 70°C
	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
	Auto.			-40°C - 125°C	-40°C - 125°C	-40°C - 125°C
V_{CC} Power Supply		5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%	5V ± 10%

DC and Operating Characteristics for Read Operation

Symbol	Parameter	Condition	Min	Max	Units
I_{LI}	Input Load Current	V_{IN} = 0V to V_{CC} (Com., Ind.)		±1.0	µA
I_{LO}	Output Leakage Current	V_{OUT} = 0V to V_{CC} (Com., Ind.)		±5.0	µA
I_{PP}[2]	V_{PP}[1] Read/Standby Current	V_{PP} = V_{CC}		±10	µA
I_{SB}	V_{CC}[1] Standby Current	I_{SB1} (CMOS), $\overline{CE}$ = V_{CC} ± 0.3V		100	µA
		I_{SB2} (TTL), $\overline{CE}$ = 2.0 to V_{CC} + 0.5V		1.0	mA
I_{CC}	V_{CC} Active Current	f = 5 MHz, I_{OUT} = 0 mA, $\overline{CE}$ = V_{IL}		25	mA
V_{IL}	Input Low Voltage		-0.6	0.8	V
V_{IH}	Input High Voltage		2.0	V_{CC} + 0.5	V
V_{OL}	Output Low Voltage	I_{OL} = 2.1 mA		0.4	V
V_{OH}	Output High Voltage	I_{OH} = -400 µA	2.4		V

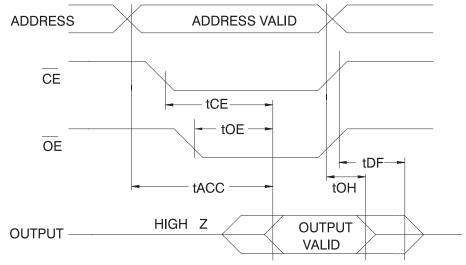Notes: 1. V_{CC} must be applied simultaneously or before V_{PP}, and removed simultaneously or after V_{PP}.

2. V_{PP} may be connected directly to V_{CC} except during programming. The supply current would then be the sum of I_{CC} and I_{PP}.

AC Characteristics for Read Operation

			AT27C020									
			-55		**-70**		**-90**		**-12**		**-15**	
Symbol	Parameter	Condition	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Units
t_{ACC}[3]	Address to Output Delay	$\overline{CE}$ = $\overline{OE}$ = V_{IL}		55		70		90		120		150	ns
t_{CE}[2]	$\overline{CE}$ to Output Delay	$\overline{OE}$ = V_{IL}		55		70		90		120		150	ns
t_{OE}[2][3]	$\overline{OE}$ to Output Delay	$\overline{CE}$ = V_{IL}		20		30		35		35		40	ns
t_{DF}[4][5]	$\overline{OE}$ or $\overline{CE}$ High to Output Float, whichever occurred first			18		20		20		30		40	ns
t_{OH}	Output Hold from Address, $\overline{CE}$ or $\overline{OE}$, whichever occurred first		7		7		0		0		0		ns

Note: 2, 3, 4, 5. See AC Waveforms for Read Operation diagram.
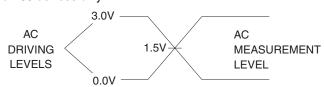
AT27C020

AC Waveforms for Read Operation[1]

Notes:
1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.
2. $\overline{OE}$ may be delayed up to t_{CE} - t_{OE} after the falling edge of $\overline{CE}$ without impact on t_{CE}.
3. $\overline{OE}$ may be delayed up to t_{ACC} - t_{OE} after the address is valid without impact on t_{ACC}.
4. This parameter is only sampled and is not 100% tested.
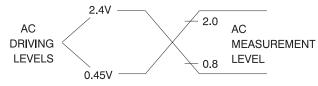5. Output float is defined as the point when data is no longer driven.

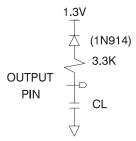## Input Test Waveforms and Measurement Levels

For -55 devices only:

t_R, t_F < 5 ns (10% to 90%)

For -70, -90, -12, -15 devices only:

t_R, t_F < 20 ns (10% to 90%)

Output Test Load

Note: CL = 100 pF including jig capacitance except -55 devices, where CL = 30 pF.

Pin Capacitance

f = 1 MHz, T = 25°C[1]

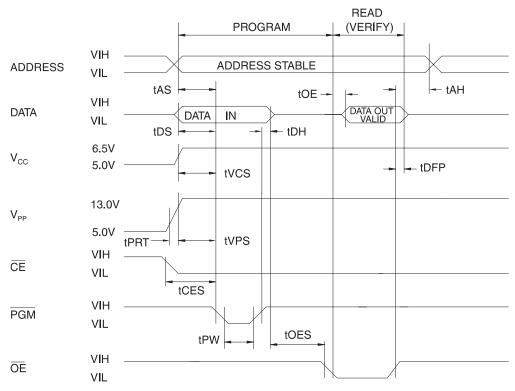| Symbol	Typ	Max	Units	Conditions
C_{IN}	4	8	pF	V_{IN} = 0V
C_{OUT}	8	12	pF	V_{OUT} = 0V

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

Programming Waveforms [1]

Notes: 1. The Input Timing reference is 0.8V for V_{IL} and 2.0V for V_{IH}.

2. t_{OE} and t_{DFP} are characteristics of the device but must be accommodated by the programmer.

3. When programming the AT27C020, a 0.1 µF capacitor is required across V_{PP} and ground to suppress voltage transients.

DC Programming Characteristics

$T_A = 25 \pm 5°C$, $V_{CC} = 6.5 \pm 0.25V$, $V_{PP} = 13.0 \pm 0.25V$

Symbol	Parameter	Test Conditions	Limits		Units
			Min	Max	
I_{LI}	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		±10	µA
V_{IL}	Input Low Level		-0.6	0.8	V
V_{IH}	Input High Level		2.0	V_{CC} + 1.0	V
V_{OL}	Output Low Voltage	I_{OL} = 2.1 mA		0.4	V
V_{OH}	Output High Voltage	I_{OH} = -400 µA	2.4		V
I_{CC2}	V_{CC} Supply Current (Program and Verify)			40	mA
I_{PP2}	V_{PP} Supply Current	$\overline{CE} = \overline{PGM} = V_{IL}$		20	mA
V_{ID}	A9 Product Identification Voltage		11.5	12.5	V

AT27C020

AC Programming Characteristics

$T_A = 25 \pm 5°C$, $V_{CC} = 6.5 \pm 0.25V$, $V_{PP} = 13.0 \pm 0.25V$

Symbol	Parameter	Test Condition [1]	Limits Min	Limits Max	Units
t_{AS}	Address Setup Time		2		µs
t_{CES}	$\overline{CE}$ Setup Time		2		µs
t_{OES}	$\overline{OE}$ Setup Time	Input Rise and Fall Times:	2		µs
t_{DS}	Data Setup Time	(10% to 90%) 20 ns	2		µs
t_{AH}	Address Hold Time		0		µs
t_{DH}	Data Hold Time	Input Pulse Levels:	2		µs
t_{DFP}	$\overline{OE}$ High to Output Float Delay[2]	0.45V to 2.4V	0	130	ns
t_{VPS}	V_{PP} Setup Time	Input Timing Reference Level:	2		µs
t_{VCS}	V_{CC} Setup Time	0.8V to 2.0V	2		µs
t_{PW}	$\overline{PGM}$ Program Pulse Width[3]	Output Timing Reference Level:	95	105	µs
t_{OE}	Data Valid from $\overline{OE}$	0.8V to 2.0V		150	ns
t_{PRT}	V_{PP} Pulse Rise Time During Programming		50		ns

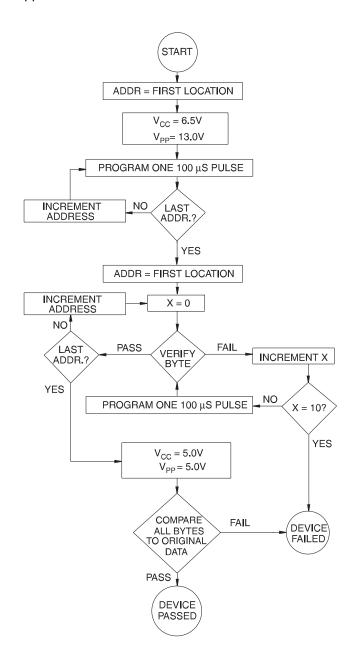Notes: 1. V_{CC} must be applied simultaneously or before V_{PP} and removed simultaneously or after V_{PP}.

2. This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven — see timing diagram.

3. Program Pulse width tolerance is 100 µs ± 5%.

Atmel's 27C020 Integrated Product Identification Code

	Pins									
Codes	A0	O7	O6	O5	O4	O3	O2	O1	O0	Hex Data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device Type	1	1	0	0	0	0	1	1	0	86

Rapid Programming Algorithm

A 100 µs $\overline{PGM}$ pulse width is used to program. The address is set to the first location. V_{CC} is raised to 6.5V and V_{PP} is raised to 13.0V. Each address is first programmed with one 100 µs $\overline{PGM}$ pulse without verification. Then a verification/reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100 µs pulses are applied with a verification after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked. V_{PP} is then lowered to 5.0V and V_{CC} to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.

Ordering Information

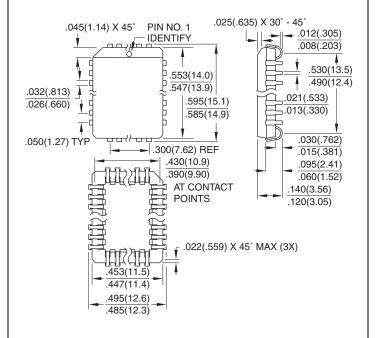| t_{ACC} (ns)	I_{CC} (mA)		Ordering Code	Package	Operation Range
	Active	**Standby**			
55	25	0.1	AT27C020-55JC AT27C020-55PC AT27C020-55TC	32J 32P6 32T	Commercial (0°C to 70°C)
	25	0.1	AT27C020-55JI AT27C020-55PI AT27C020-55TI	32J 32P6 32T	Industrial (-40°C to 85°C)
70	25	0.1	AT27C020-70JC AT27C020-70PC AT27C020-70TC	32J 32P6 32T	Commercial (0°C to 70°C)
	25	0.1	AT27C020-70JI AT27C020-70PI AT27C020-70TI	32J 32P6 32T	Industrial (-40°C to 85°C)
90	25	0.1	AT27C020-90JC AT27C020-90PC AT27C020-90TC	32J 32P6 32T	Commercial (0°C to 70°C)
	25	0.1	AT27C020-90JI AT27C020-90PI AT27C020-90TI	32J 32P6 32T	Industrial (-40°C to 85°C)
	25	0.1	AT27C020-90JA AT27C020-90PA	32J 32P6	Automotive (-40°C to 125°C)
120	25	0.1	AT27C020-12JC AT27C020-12PC AT27C020-12TC	32J 32P6 32T	Commercial (0°C to 70°C)
	25	0.1	AT27C020-12JI AT27C020-12PI AT27C020-12TI	32J 32P6 32T	Industrial (-40°C to 85°C)
	25	0.1	AT27C020-12JA AT27C020-12PA	32J 32P6	Automotive (-40°C to 125°C)
150	25	0.1	AT27C020-15JC AT27C020-15PC AT27C020-15TC	32J 32P6 32T	Commercial (0°C to 70°C)
	25	0.1	AT27C020-15JI AT27C020-15PI AT27C020-15TI	32J 32P6 32T	Industrial (-40°C to 85°C)
	25	0.1	AT27C020-15JA AT27C020-15PA	32J 32P6	Automotive (-40°C to 125°C)

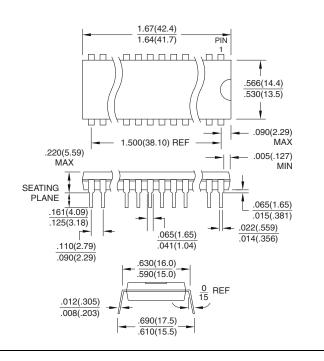| Package Type	
32J	32-lead, Plastic J-leaded Chip Carrier (PLCC)
32P6	32-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
32T	32-lead, Plastic Thin Small Outline Package (TSOP)

Packaging Information

32J, 32-lead, Plastic J-leaded Chip Carrier (PLCC)
Dimensions in Inches and (Millimeters)
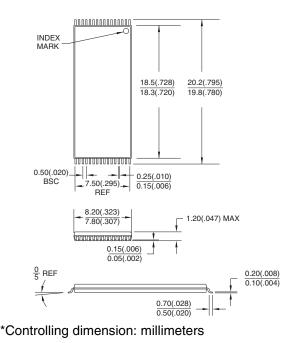JEDEC STANDARD MS-016 AE

32P6, 32-lead, 0.600" Wide, Plastic Dual Inline Package (PDIP)
Dimensions in Inches and (Millimeters)

32T, 32-lead, Plastic Thin Small Outline Package (TSOP)
Dimensions in Millimeters and (Inches)*
JEDEC OUTLINE MO-142 BD

*Controlling dimension: millimeters

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